

Abstract

A heat sink or heat transfer device particularly for integrated circuits, uses a phase change working fluid in a cyclic flow path having at least one evaporator that serves multiple heat sources. The evaporator can be an integral vessel made of thermally conductive material to which the multiple heat sources are coupled, preferably at evaporation points that are placed on opposite sides of a fluid reservoir for the liquid phase of the working fluid that feeds the evaporation points via capillary flow through a wicking material.

HBG\118177.2